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PATENT AND TRADEMARK OFFICE. PLEASE RECORD THE ATTACHED

1. Name of conveying parties:

CHUNG, Se-jin
KIM Dong-bum

Additional name(s) of conveying party(ies) attached?

Yes No

2. Name and address of receiving party:

Name: SAMSUNG ELECTRONICS CO., LTD.
Address: 416, Maetan-dong, Yeongtong-gu, Suwon-si,
Gyeonggi-do, Republic of Korea

Additional name(s) of receiving party(ies) attached?

Yes No

113261 U.S. PTO
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3. Nature of Conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution Date: May 15, 2006

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: May 15, 2006

A. Patent Application No.(s)

Title: MASK FOR SEQUENTIAL LATERAL SOLIDIFICATION
AND METHOD OF MANUFACTURING THE SAME

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Howard R. Popper
Internal Address: MACPHERSON, KWOK CHEN & HEID LLP
Street Address: 1762 Technology Drive, Suite 226
City San Jose State CA Zip 95110

6. Total number of applications and patents involved: One (1)

7. Total fee (37 CFR 3.41): \$40.00

Authorized to be charged to Deposit Account No. 50-2257.
 Charge Deposit Account No. 50-2257 for any additional fees required for this conveyance and credit Deposit Account No. 50-2257 any amounts overpaid

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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David W. Heid, Reg. No. 25,875
Name of Person Signing

David W. Heid
Signature

Aug 4, 2006
Date

Total number of pages comprising cover sheet: 2

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ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Se-jin CHUNG	of	#301-1204 I-PARK, Seowon Maeul 3-danji, 860 Sanghyeon-dong, Yongin-si, Gyeonggi-do, Republic of Korea
Dong-bum KIM	of	#G-1101 Samsung Tower Palace, Dogok 2-dong, Gangnam-gu, Seoul, Republic of Korea

hereby sell, assign and transfer to **SAMSUNG ELECTRONICS CO., LTD.**, a corporation, having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in

MASK FOR SEQUENTIAL LATERAL SOLIDIFICATION AND METHOD OF MANUFACTURING THE SAME

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 15th day of May, 2006.

Se-jin Chung

Se-jin CHUNG

WITNESSED:

 Signature

 Date

 Type or print name of witness

Executed this 15th day of May, 2006.

Dong-bum Kim

Dong-bum KIM

WITNESSED:

 Signature

 Date

 Type or print name of witness